

Crystal-less™ Configurable Two-Output Clock Generator

Features

- Two Simultaneous CMOS Outputs
 - Output 1 Range: 2.3 MHz to 170 MHz
 - Output 2 Range: 2.3 MHz to 170 MHz
- Low RMS Phase Jitter: <1 ps (typ.)
- High Stability: ± 25 ppm, ± 50 ppm
- Wide Temperature Range
 - Automotive: -40°C to $+125^{\circ}\text{C}$
 - Ext. Industrial -40°C to $+105^{\circ}\text{C}$
 - Industrial -40°C to $+85^{\circ}\text{C}$
 - Ext. Commercial -20°C to $+70^{\circ}\text{C}$
- High Supply Noise Rejection: -50 dBc
- High Shock and Vibration Immunity
 - Qualified to MIL-STD-883
- High Reliability
 - 20x higher MTBF than crystal-based clock generator designs
- Supply Range of 2.25V to 3.6V
- Lead Free and RoHS-Compliant

Applications

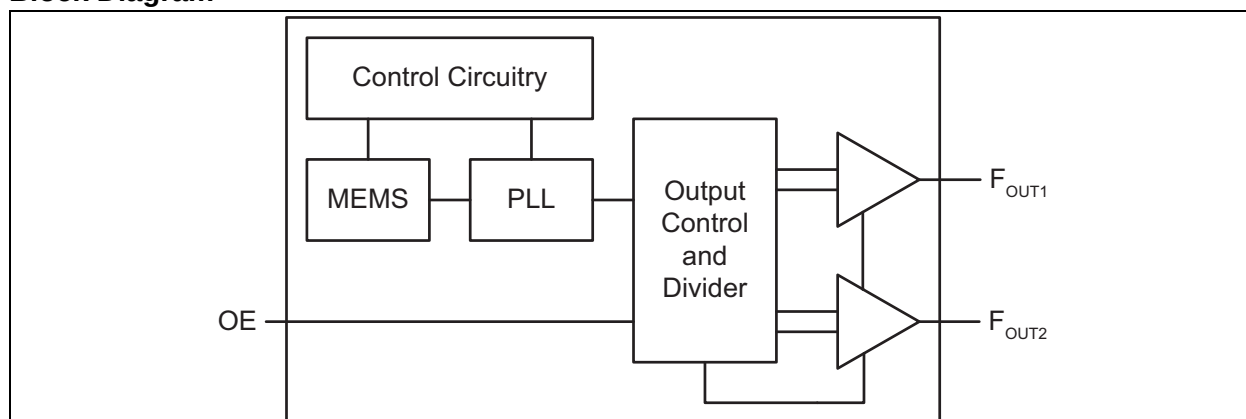
- Consumer Electronics
- Camera and Imaging Modules
- Home Automation
- Industrial and Power Conversion
- Mobile Communications, Internet, and Sensor Devices
- Solid State, Hard Drive, and Flash Drive Storage

General Description

The DSC2311 is a crystal-less™ clock generator that is factory-configurable to simultaneously output two separate frequencies from 2.3 MHz to 170 MHz. The clock generator uses proven silicon MEMS technology to provide low jitter and high frequency stability across a wide range of supply voltages and temperatures. By eliminating the external quartz crystal, crystal-less clock generators significantly enhance reliability and accelerate product development, while meeting stringent clock performance criteria for a variety of consumer electronics, communications, and storage applications.

DSC2311 has an Output Enable/Disable feature that allows it to disable the outputs when OE is low. The device is available in a space-saving 6-pin 2.5 mm x 2.0 mm crystal-less VDFN package that uses only a single external bypass capacitor. This requires a PCB footprint equivalent to that of a 1.0 mm x 1.0 mm crystal-based clock generator.

Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage	–0.3V to +4.0V
Input Voltage	–0.3V to $V_{DD}+0.3V$
ESD Protection (HBM)	4 kV
ESD Protection (CDM)	1.5 kV

† **Notice:** Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

Specifications: $V_{DD} = 3.3V$; $T_A = +25^{\circ}C$ unless otherwise specified.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Supply Voltage (Note 1)	V_{DD}	2.25	—	3.6	V	—
Supply Current (Note 2)	I_{DD}	—	21	23	mA	EN pin low. All outputs disabled.
Frequency Stability (Note 3)	Δf	—	—	± 25	ppm	Includes frequency variations due to initial tolerance, temperature, and power supply voltage.
		—	—	± 50		
Aging	Δf	—	—	± 5	ppm	One year at $+25^{\circ}C$
Start-up Time (Note 4)	t_{SU}	—	—	5	ms	$T = +25^{\circ}C$
Input Logic Levels	V_{IH}	$0.75 \times V_{DD}$	—	—	V	Input logic high
	V_{IL}	—	—	$0.25 \times V_{DD}$		Input logic low
Output Disable Time	t_{DA}	—	—	5	ns	—
Output Enable Time	t_{EN}	—	—	20	ns	—
Pull-Up Resistor (Note 2)	—	—	40	—	k Ω	Pull-up exists on all digital IO
Output Logic Levels	V_{OH}	$0.9 \times V_{DD}$	—	—	V	Output logic high, $I = \pm 6$ mA
	V_{OL}	—	—	$0.1 \times V_{DD}$		Output logic low, $I = \pm 6$ mA
Output Transition Time	t_R	—	1.1	2.0	ns	Rise time. 20% to 80%; $C_L = 15$ pF
	t_F	—	1.4	2.0		Fall time. 20% to 80%; $C_L = 15$ pF
Frequency	f_0	2.3	—	170	MHz	Commercial/Industrial temp. range
		3.3	—	100		Automotive temp. range
		3.3	—	170		Extended Industrial temp. range

- Note 1:** Pin 4 V_{DD} should be filtered with a 0.01 μF capacitor.
- 2:** Output is enabled if Enable pad is floated or not connected. Operating current = disabled current + ΔI_{DD} from F_{OUT1} + ΔI_{DD} from F_{OUT2} . See [Current Consumption](#) graph for more information.
- 3:** For other ppm stabilities, please contact the factory.
- 4:** t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.
- 5:** Period jitter includes crosstalk from adjacent output.

ELECTRICAL CHARACTERISTICS (CONTINUED)

Specifications: $V_{DD} = 3.3V$; $T_A = +25^{\circ}C$ unless otherwise specified.

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Output Duty Cycle	SYM	45	—	55	%	—
Period Jitter (Note 5)	J_{PER}	—	3	—	ps_{RMS}	$F_{O1} = F_{O2} = 25\text{ MHz}$
Integrated Phase Noise	J_{CC}	—	0.3	—	ps_{RMS}	200 kHz to 20 MHz @ 25 MHz
		—	0.38	—		100 kHz to 20 MHz @ 25 MHz
		—	1.7	2		12 kHz to 20 MHz @ 25 MHz

- Note 1:** Pin 4 V_{DD} should be filtered with a 0.01 μF capacitor.
- 2:** Output is enabled if Enable pad is floated or not connected. Operating current = disabled current + ΔI_{DD} from F_{OUT1} + ΔI_{DD} from F_{OUT2} . See [Current Consumption](#) graph for more information.
- 3:** For other ppm stabilities, please contact the factory.
- 4:** t_{SU} is time to 100 ppm stable output frequency after V_{DD} is applied and outputs are enabled.
- 5:** Period jitter includes crosstalk from adjacent output.

TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Sym.	Min.	Typ.	Max.	Units	Conditions
Temperature Ranges						
Operating Temperature Range (T)	T _A	-20	—	+70	°C	Ordering Option E
	T _A	-40	—	+85	°C	Ordering Option I
	T _A	-40	—	+105	°C	Ordering Option L
	T _A	-40	—	+125	°C	Ordering Option M
Junction Temperature	T _J	—	—	+150	°C	—
Storage Temperature Range	T _S	-40	—	+150	°C	—
Soldering Temperature Range	—	—	—	+260	°C	40 sec. max.

Note 1: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature, and the thermal resistance from junction to air (i.e., T_A, T_J, θ_{JA}). Exceeding the maximum allowable power dissipation will cause the device operating junction temperature to exceed the maximum +125°C rating. Sustained junction temperatures above +125°C can impact the device reliability.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 2-1](#).

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Description
1	ENABLE	Output Enable for both CLK0 and CLK1.
2	N/C	Do not connect.
3	GROUND	Ground.
4	CLK0	Clock Output 0 (CMOS).
5	CLK1	Clock Output 1 (CMOS).
6	VDD	Supply Voltage.

3.0 OUTPUT WAVEFORM

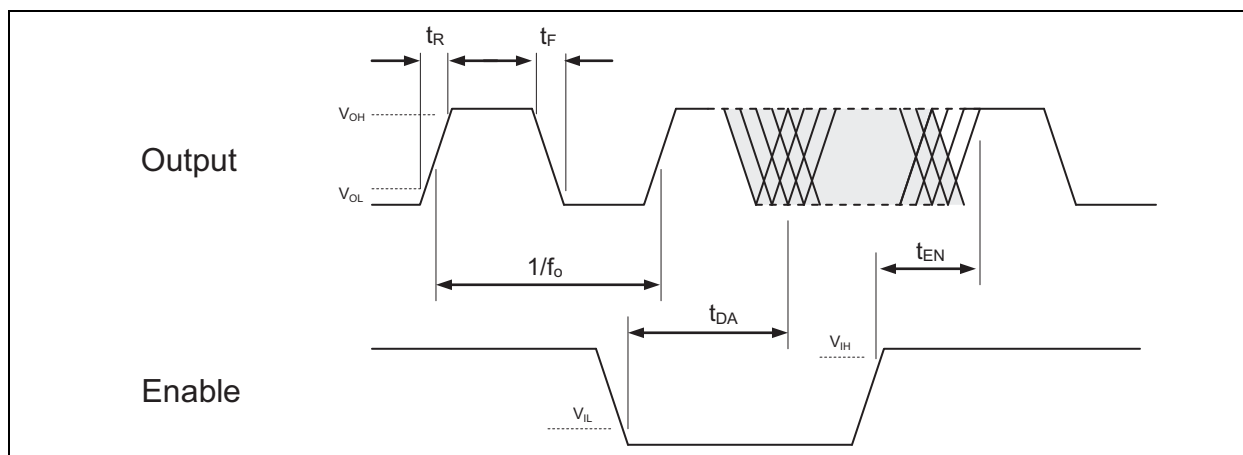


FIGURE 3-1: OE Function and Output Waveform: LVCMOS.

4.0 CURRENT CONSUMPTION

Total Current = Disabled Current + $\Delta I_{DD} F_{OUT1}$ + $\Delta I_{DD} F_{OUT2}$

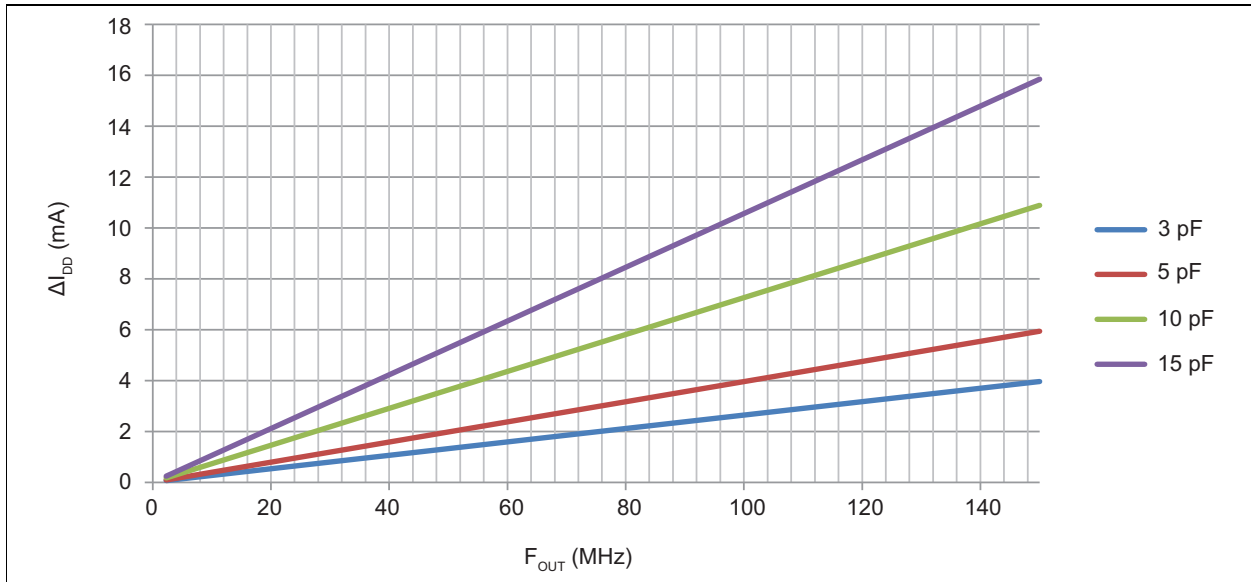
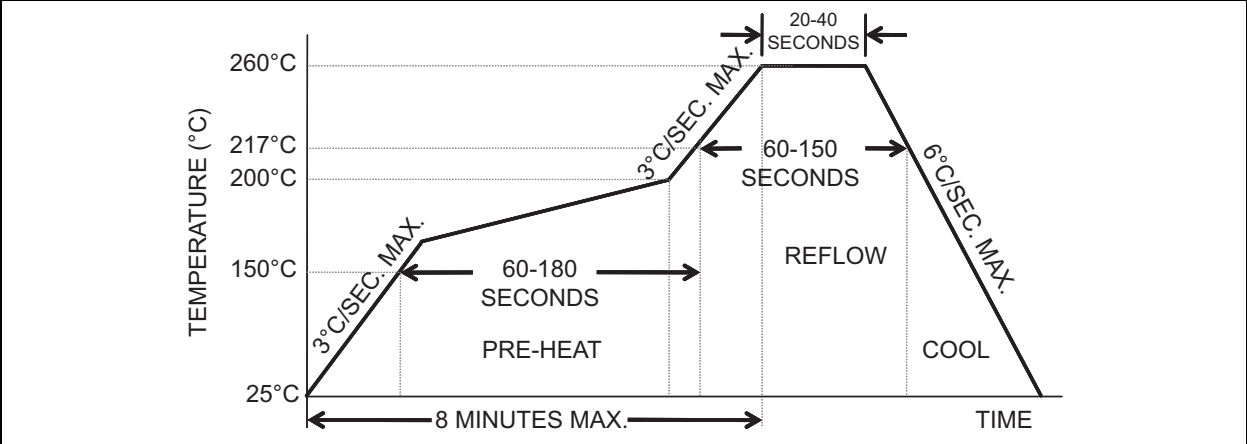


FIGURE 4-1: ΔI_{DD} / Output vs. Frequency and Load @ 3.3V V_{DD}

5.0 SOLDER REFLOW PROFILE



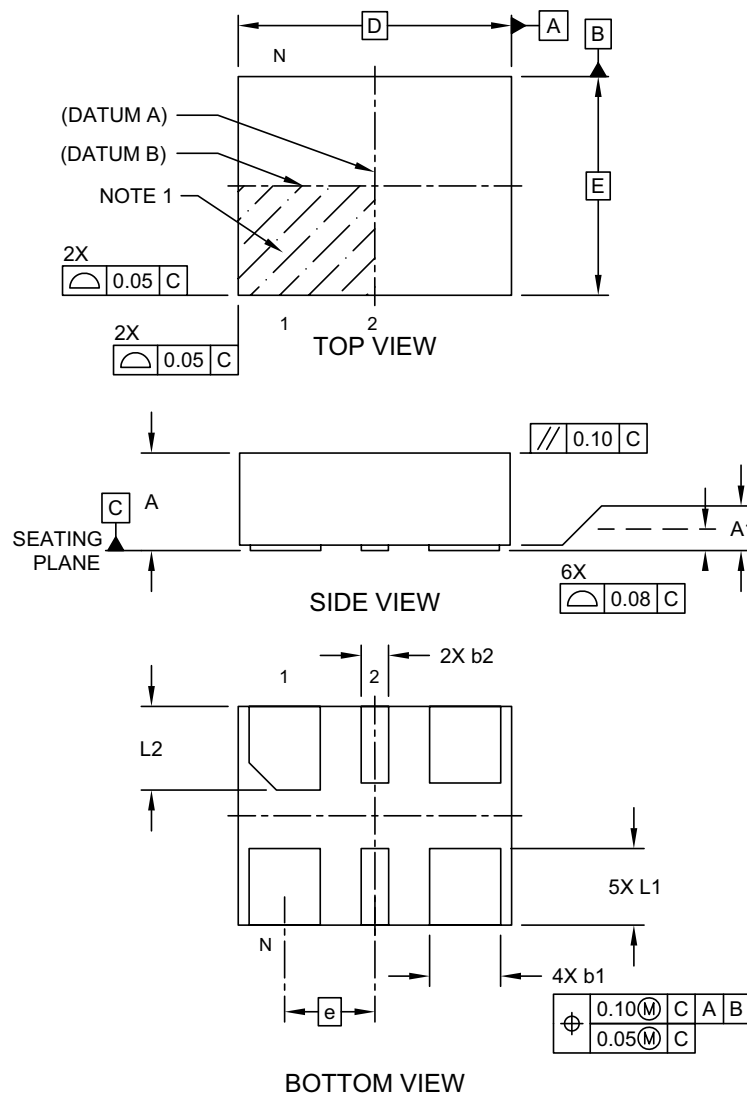
6-PIN QFN MSL 1 @ 260°C refer to JSTD-020C	
Ramp-Up Rate (200°C to Peak Temp)	3°C/sec. max.
Preheat Time 150°C to 200°C	60-180 sec.
Time Maintained above 217°C	60-150 sec.
Peak Temperature	255°C to 260°C
Time within 5°C of Actual Peak	20-40 sec.
Ramp-Down Rate	6°C/sec. max.
Time 25°C to Peak Temperature	8 minutes max.

6.0 PACKAGE MARKING INFORMATION

6-Lead VDFN 2.5 mm x 2.0 mm Package Outline and Recommended Land Pattern

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

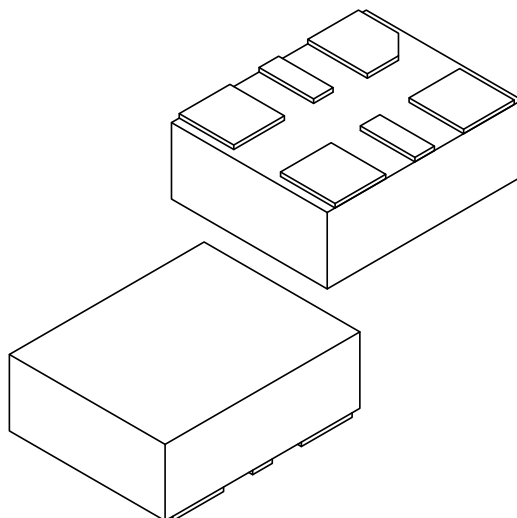
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-1005A Sheet 1 of 2

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	6		
Pitch	e	0.825 BSC		
Overall Height	A	0.80	0.85	0.90
Standoff	A1	0.00	0.02	0.05
Overall Length	D	2.50 BSC		
Overall Width	E	2.00 BSC		
Terminal Width	b1	0.60	0.65	0.70
Terminal Width	b2	0.20	0.25	0.30
Terminal Length	L1	0.60	0.70	0.80
Terminal Length	L2	0.665	0.765	0.865

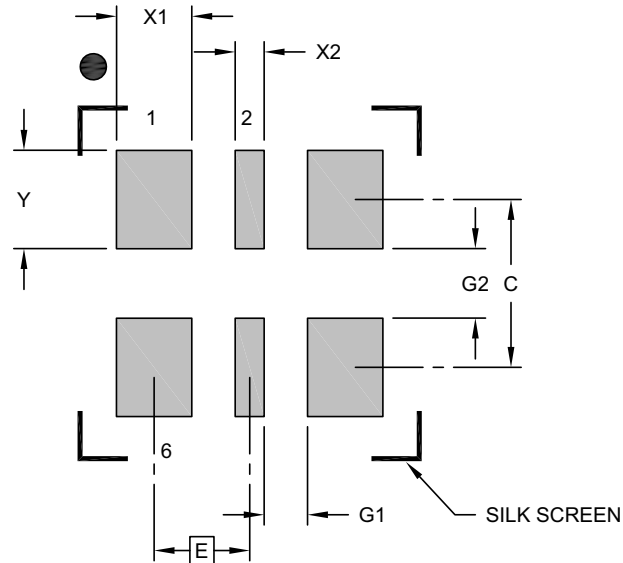
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1005A Sheet 2 of 2

6-Lead Very Thin Dual Flatpack No-Leads (J7A) - 2.5x2.0 mm Body [VDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.825 BSC		
Contact Pad Width (X4)	X1			0.65
Contact Pad Width (X2)	X2			0.25
Contact Pad Length (X6)	Y			0.85
Contact Pad Spacing	C		1.45	
Space Between Contacts (X4)	G1	0.38		
Space Between Contacts (X3)	G2	0.60		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process

Microchip Technology Drawing C04-3005A

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (September 2016)

- Converted Micrel data sheet DSC2311 to Microchip DS20005611A.
- Minor text changes throughout.
- Package name updated to VDFN.

NOTES:

NOTES:

Note the following details of the code protection feature on Microchip devices:

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